Maxence Bouvier, PhD

LinkedIn | GoogleScholar

I discovered AI's potential six years ago at IBM, inspiring my Ph.D. studies to build energy-efficient machine learning vision systems. At Sony, I have been leading a project on multimodal transformer models for low power vision systems. I mentored many successful students during their thesis and internships, which helped me patent several ideas. I'm now eager to create AI solutions that will impact millions.

EXPERIENCE

SONY Senior AI Research Engineer

o Sparsity Exploitation in Transformers

Zurich, Switzerland Aug 2023 - Present

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- * Engineered an asynchronous PointNet-based embedding, enabling continuous spatio-temporal data conversion into dense tensors for seamless, ongoing feeding of Transformer models - (1 paper, 1 patent.)
 - Designed an NPU-compatible sparse scaled-dot-product-attention per-block module for highly efficient sparse attention in Transformers, achieving more than 50% FLOPs reduction during inference and higher accuracy.
- o SLAM Enhanced AI Training: Enhanced performance by incorporating a cutting-edge SLAM pipeline for multi-modal training process, achieving 6x faster model convergence and a 15% boost in accuracy.

AI Research Engineer June 2022 - Aug 2023

o SW/HW Co-Design Automation with Neural Architecture Search

- * Built an AI-driven, Hardware-Aware Neural Architecture Search framework. Enabled to automatically reduce model to 8% FLOP cost while losing only 4% relative accuracy.
- * Integrated a Design Space Exploration software in the NAS loop to estimate energy and latency of model execution.
- o Transformer Hardware Acceleration Survey: Conducted a literature study, featured in CTO's strategic report.
- **Vision Transformer for Image Generation**
 - * Implemented an AI model leveraging CNN and Transformer architectures to realize advanced frame generation. (1 patent.)
 - * Built a live demo of the model, from image sensor to application. This led to 2 major collaborations with other teams.
 - * Converted the model as an API to simplify sharing across teams and projects.
- o **Software Maintainer**: Responsible for the CI of a few Python libraries shared among teams.

STMicroelectronics

Grenoble, France Apr 2021 - May 2022

Hardware Design Engineer

- o CPU Design and Automation * Created a toolbox to automate component assembly of the Trace and Debug subsystem with ARM's Armv9-A SoC modules.
 - * Developed an RTL generator for STM32 MPU SoC, streamlining the design of a multi-clock domain reset and clock control for over 300 peripherals.
- o CPU Benchmarking: Conducted CoreMark benchmarking on a multi-core MPU SoC, highlighting significant performance gains (up to 6x) through compiler updates.

CEA LETI Grenoble, France

Doctoral Researcher on AI and Hardware Design

Apr 2018 - Apr 2021

- o Neuromorphic Hardware Analysis: Conducted a comprehensive bibliographic study on scalable, multi-chip, distributed neuromorphic hardware, leading to a widely cited publication in ACM JETC. - (1 paper.)
- o ULP NPU Design: Built (RTL design, synthesis and layout) an ultra-low power sparse AI accelerator, setting energy efficiency records (2.86pJ/OP in 28nm) and enabling seamless integration for 3D-stacked imagers. - (1 paper, 2 patents.)
- EB VIO/SLAM Pipeline and Object Detection Innovation: Developed an Event-Based VIO/SLAM pipeline with ego-motion compensation, leading to a solution for detecting moving objects. - (1 patent.)

IBM Research

Yorktown Heights, NY, USA

Feb 2017 - Aug 2017

Intern Hardware Engineer

- Automated wafer-scale memory device characterization, reducing execution time from days to hours.
- Contributed to the optimization of PCM technologies for Compute-in-Memory-based AI acceleration. (1 paper, 1 patent.)

SKILLS

- Languages: Python, C, C++, MATLAB, SystemVerilog, VHDL, LaTeX
- Libraries: PyTorch, MLFlow, ONNX, Numpy, Pandas, ROS, OpenCV, CUDA
- Softwares: Git, GitLab CI, EDA (Cadence, Synopsys, Mentor), VSCode, PowerPoint Expert

EDUCATION

- Grenoble Alpes University | Ph.D. in Computer Science
- **EPFL** | "M.Eng. in Electronics (Highest Honors)"
- **Grenoble Institute of Technology** | B.Eng. in Electronics

Apr 2018 – Apr 2021 | Grenoble, France Sep 2015 – Sep 2017 | Lausanne, Switzerland

Sep 2012 – Sep 2015 | Grenoble, France